

Providing practical information to the converting and packaging industries A communication from the PLACE Division of TAPPI

in cooperation with Paper, Film & Foil CONVERTER

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Short Course Receives Rave Reviews

Attendees at the Troubleshooting For Extrusion Coating And Flexible Packaging Converters Short Course held June 3–6, 2002, at the Radisson Hotel & Conference Center in Green Bay, WI, were very enthusiastic in their ratings for the event. The 115 registrants gave the meeting a rating over 95% for excellence in teaching methods, content, and opportunities for interaction available during the four-day meeting. Lou Piffer of Egan Davis-Standard and Dante Ferrari of AT Plastics were the co-chairmen for the course. The program combined two previously successful TAPPI short courses into one novel format for a strong technical program with several real examples of converting problems and their solutions. The case studies interspersed with formal presentations allowed participants to engage in active problem solving themselves.

Typical comments from the people at the course noted that the course included a wide variety of topics with in-depth coverage and appreciation for the two networking opportunities. Comments ranged from being able to "use this information as a tool box" to learning how "to run our operation more efficiently." One attendee noted that he can now "teach less experienced operators troubleshooting techniques," and another observed that he now has a "better insight into the different fields of converting ... that will make my job easier." "I was very happy with the instructors," stated one person.

Participants in the course learned about the latest materials and equipment used in the extrusion coating and flexible packaging industries. The course covered the ba-*Continued on page* 176

Hot Melt Group Calls For Papers

To show its full dedication to all global aspects of the hot melt industry, the TAPPI Hot Melt Symposium will now be the TAPPI GLOBAL HOT MELT Symposium. A major goal of the next meeting will be revitalization of networking among all members of the global hot melt industry.

The TAPPI Hot Melt Committee belongs to the PLACE Division. The division comprises professionals working in flexible packaging, laminations, adhesives, coatings, and extrusions. Because of the synergies between the TAPPI Hot Melt Committee and its parent division, the committee has announced that its 2003 symposium will occur with the annual PLACE Division Conference. The joint meeting called the "2003 TAPPI PLACE Conference and GLOBAL HOT MELT Symposium" will be August 3–7 at the Rosen Centre Hotel in Orlando, FL. George Altounian of Eastman Chemical Co., the chair of the GLOBAL HOT MELT Symposium, says, "This joint format for the two meetings provides an exceptional opportunity for registrants. They can experience the cross fertilization and synergy available through exposure to the many technical presentations covering all aspects of hot melts and converting and packaging products."

A New Technology Showcase session will allow participants to present their products and technologies developed over the last 18 months in a commercial format. A table top reception following this session will provide networking opportunities.

The symposium will concentrate on reactive hot melt technologies and application processes. "We seek papers dealing with moisture and radiation curing technologies," said John Tangen of 3M Adhesives Division, the executive secretary of the Hot Melt Committee. "We also want papers from users concerning furniture, doors, and windows and automotive OEM and industrial assembly operations.

Robert Forsyth, Consultant, the executive vice-chair of the Hot Melt Committee added, "This will be the biggest and best hot melt meeting our committee has ever presented. Emphasizing the global aspects will enable the meeting to provide valuable information about the hot melt industry worldwide. An in-*Continued on page 176*



For information about the PLACE Division of TAPPI, access the TAPPI web page at www.TAPPI.org. To obtain the complete papers whose expanded summaries appear in this section, go to the TAPPI web site at www.TAPPI.org. Then click on "the PLACE" in the section designated Journals.

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